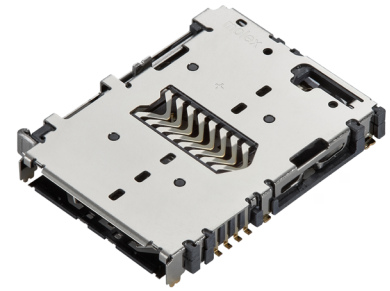


mSD/nSIM 3-in-3 Stacked Socket, Pin-Eject Type

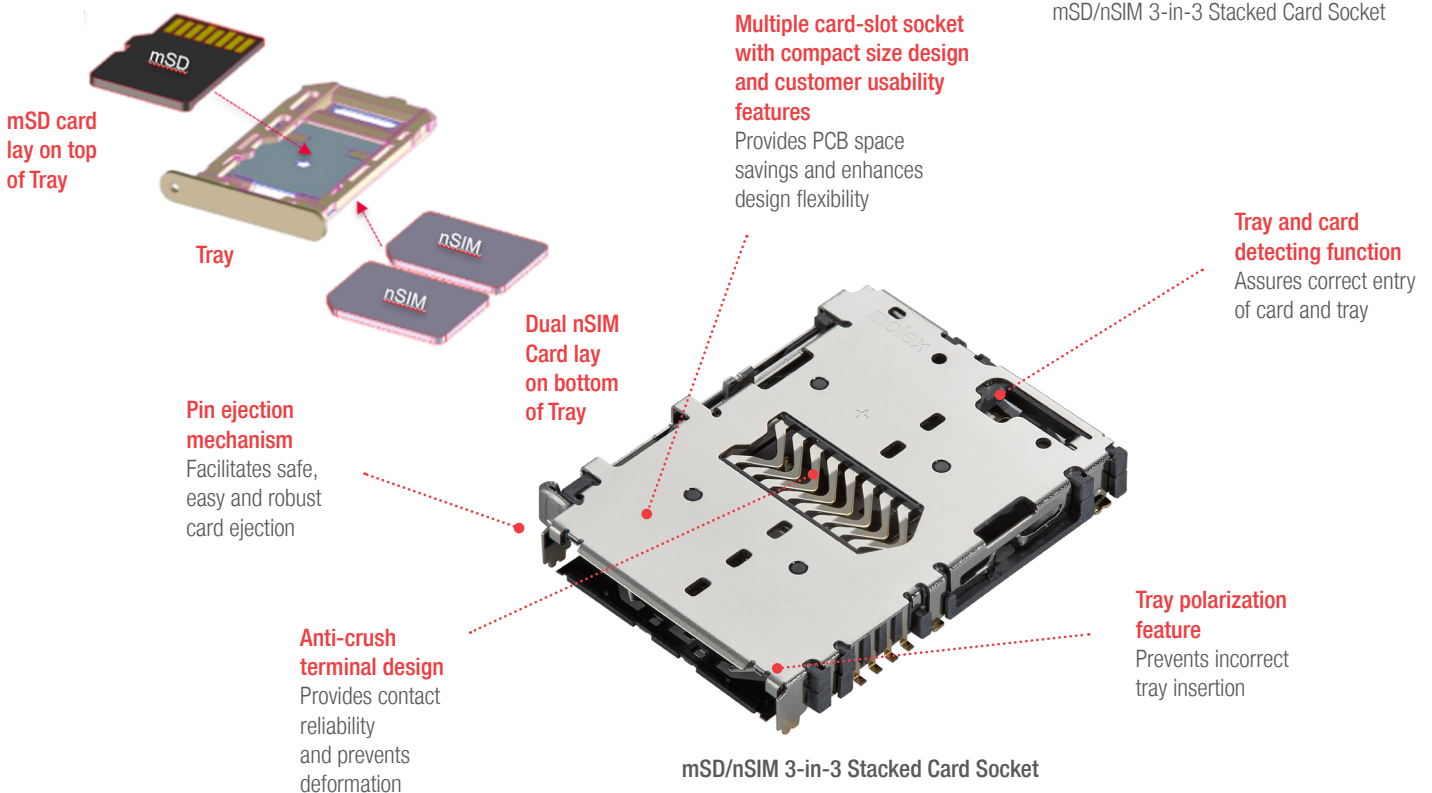
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Molex's compact and low-profile mSD and dual-nSIM 3-in-3 Stacked Card Socket with secure electrical contact, pin-eject function and easy card insertion and removal, delivers PCB space-savings making it ideal for ultra-thin electronic devices requiring removable and reliable multi-card connectivity



mSD/nSIM 3-in-3 Stacked Card Socket

Features and Advantages



Applications

Smart Phones/Mobile devices

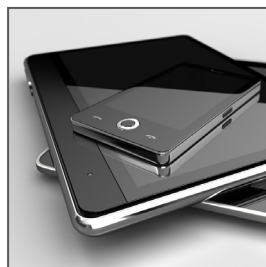
- Mobile Devices
- Tablet PCs

Commercial & Consumer

- Internet of Things (IoT) Applications
- Home Appliances
- Smart Speakers
- AR/VR

Industrial

- UAVs / Drones
- Security Systems
- Smart Meters



Mobile Devices



Smart Speaker



UAVs / Drones

mSD/nSIM 3-in-3 Stacked Socket, Pin-Eject Type

molex

Specifications

REFERENCE INFORMATION

Packaging: Embossed tape
Designed In: Millimetres
RoHS: Yes
Halogen Free: Low halogen

ELECTRICAL

Voltage (max.): 10V
Current (max.): 0.5A
Contact Resistance (max.):
 mSD / nSIM - 100 milliohms
 Detector/Switch - 200 milliohms
Dielectric Withstanding Voltage: 500V AC (rms)
Insulation Resistance (min.): 1000 Megohms

MECHANICAL

Tray Insertion Force (max.): 10N
Pin Ejection Force: 4 to 13N
Contact Normal Force (Initial):
 mSD: 0.3N min/PIN
 nSIM: 0.35N min/PIN
Durability: 2,000 cycle
Heat Resistance: 85±2°C x 96Hr
Cold Resistance: -40±3°C x 96Hr

PHYSICAL

Housing: LCP
Contact: Copper Alloy
Shell & Detector : Stainless Steel
Eject Bar : Stainless Steel
Hinge : Stainless Steel
Operating Temperature: -40 to +85°C

www.molex.com/product/memory/simcard.html

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